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8. A method for manufacturing a semiconductor apparatus comprising:

forming a release layer including a semiconductor device over a first substrate;

coating an organic resin film that melts with solvent over the release layer;

bonding a second substrate to the organic resin film with a first two-sided tape to sandwich the release layer and the organic resin film between the first substrate and the second substrate;

bonding a third substrate to the first substrate with a second two-sided tape;

separating the first substrate to which the third substrate is bonded from the release layer by a physical means;

bonding a fourth substrate to the release layer to sandwich the release layer between the second substrate and the fourth substrate;

separating the release layer and the first two-sided tape from the second substrate;

separating the release layer from the first two-sided tape; and

removing the organic resin film with solvent.

9. A method according to claim 8, wherein the solvent is water or alcohol.

10. A method according to claim 8, wherein adhesiveness of the first two-sided tape and the second substrate in the seventh process is stronger than that of the release layer and the fourth substrate.

11. A method for manufacturing a semiconductor apparatus comprising:

forming a release layer including a semiconductor device over a first substrate;

coating an organic resin film that melts with solvent over the release layer;

bonding a second substrate to the organic resin film with a first two-sided tape to sandwich the release layer and the organic resin film between the first substrate and the second substrate;

bonding a third substrate to the first substrate with the second two-sided tape;

separating the first substrate to which the third substrate is bonded from the release layer by a physical means;

bonding a fourth substrate to the release layer to sandwich the release layer between the second substrate and the fourth substrate;

separating the release layer and first two-sided tape from the second substrate;

separating the release layer from the first two-sided tape;

removing the organic resin film with solvent; and

bonding a fifth substrate to the release layer with a second adhesive to sandwich the release layer between the fourth substrate and the fifth substrate.

12. A method according to claim 11, wherein the solvent is

water or alcohol.

13. A method according to claim 11, wherein adhesiveness of the first two-sided tape and the second substrate in the seventh process is stronger than that of the release layer and the fourth substrate.

14. A method according to claim 11, wherein the first substrate is a glass substrate, the second and the third substrates are a quartz substrate or a metal substrate, and the fourth substrate and the fifth substrate are plastic substrates.

15. A method according to claim 11, wherein the first substrate is a glass substrate, the second and the third substrates are a quartz substrate or a metal substrate, and among the fourth and the fifth substrate, one is a plastic substrate being transparent to light and another is a plastic substrate having thermal conductivity.

16. A method according to claim 11, wherein the fourth or the fifth substrate is a plastic substrate on the surface of which a SiN_x film, a SiN_xO_y film, an AlN_x film, or an AlN_xO_y film is formed.

17. A method for manufacturing a semiconductor apparatus comprising:

forming a release layer including a TFT over a first substrate;

coating an organic resin film that melts with solvent over the release layer;

bonding a second substrate to the organic resin film with a first two-sided tape to sandwich the release layer and the organic resin film between the first substrate and the second substrate;

bonding a third substrate to the first substrate with the second two-sided tape;

separating the first substrate to which the third substrate is bonded from the release layer by a physical means;

bonding a fourth substrate to the release layer with a first adhesive to sandwich the release layer between the second substrate and the fourth substrate;

separating the release layer and the first two-sided tape from the second substrate;

separating the release layer from the first two-sided tape;

removing the organic resin film with solvent;

fabricating a light-emitting device including an organic compound over the release layer; and

bonding a fifth substrate for sealing the light-emitting device to the release layer with a second adhesive to sandwich the release layer between the fourth substrate and the fifth substrate.

18. A method according to claim 17, wherein the solvent is water or alcohol.

19. A method according to claim 17, wherein adhesiveness of the first two-sided tape and the second substrate in the seventh process is stronger than that of the release layer and the fourth substrate.

20. A method according to claim 17, wherein the solvent is water or alcohol.

21. A method according to claim 17, wherein adhesiveness of the first two-sided tape and the second substrate in the seventh process is stronger than that of the release layer and the fourth substrate.

22. A method according to claim 17, wherein the first substrate is a glass substrate, the second and the third substrates are a quartz substrate or a metal substrate, and the fourth substrate and the fifth substrate are plastic substrates.

23. A method according to claim 17, wherein the first substrate is a glass substrate, the second and the third substrates are a quartz substrate or a metal substrate, and among the fourth and the fifth substrate, one is a plastic substrate being transparent to light and another is a plastic substrate having thermal conductivity.

24. A method according to claim 17, wherein the fourth or the fifth substrate is a plastic substrate on the surface of which a SiN_x film, a SiN_xO_y film, an AlN_x film, or an AlN_xO_y film is formed.